

200mA, 40V Schottky Barrier Diode

FEATURES

- Fast switching device
- Surface mount device type

• For switching power supply

- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant

APPLICATIONS

• Low stored charge

• Adapters

Inverter

• Halogen-free according to IEC 61249-2-21

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	200	mA	
V _{RRM}	40	V	
V _F at I _F =40mA	1.0	V	
T _{J MAX}	125	°C	
Package	SOD-523F		





- MECHANICAL DATA
- Case: SOD-523F
- Molding compound meets UL 94 V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band
- Weight: 1.60 mg (approximately)

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)			
PARAMETER	SYMBOL	BAS40M5	UNIT
Marking code on the device		40	
Power dissipation	P _D	200	mW
Repetitive peak reverse voltage	V _{RRM}	40	V
Non-repetitive peak reverse voltage	V _{RM}	40	V
Forward current	I _F	200	mA
Non-repetitive peak forward surge current @ t=8.3ms	I _{FSM}	0.5	А
Junction temperature range	TJ	-50 to +125	°C
Storage temperature range	T _{STG}	-50 to +125	°C



BAS40M5

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PARAMETER	CONDITIONS	SYMBOL	MIN	MAX	UNIT
	I _F = 1mA, T _J = 25°C			0.38	
Forward voltage ⁽¹⁾	I _F = 10mA, T _J = 25°C	V _F	-	0.50	V
	I _F = 40mA, T _J = 25°C			1.00	
Reverse voltage (2)	I _R = 10μΑ, Τ _J = 25°C	V _R	40	-	V
Reverse current ⁽²⁾ $V_R = 25V, T_J = 25^{\circ}C$		I _R	-	1	μA
capacitance $f = 1MHz, V_R = 0V$		С	-	5	pF
Reverse recovery time $I_F = I_R = 10 \text{mA}$ $I_{RR} = 1 \text{mA}, R_L = 100\Omega$		t _{rr}	-	5	ns

Notes:

1. Pulse test with PW=0.3 ms

2. Pulse test with PW=30 ms

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
BAS40M5 RSG	SOD-523F	8K / 7" Reel	



CHARACTERISTICS CURVES

($T_A = 25^{\circ}C$ unless otherwise noted)



Fig.1 Typical Forward Characteristics

Fig.2 Typical Reverse Characteristics

Fig.3 Typical Capacitance Characteristics

Capacitance (pF)

Fig.4 Power Derating Curve







PACKAGE OUTLINE DIMENSION



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	0.50	0.77	0.020	0.030
b	0.25	0.40	0.010	0.016
с	0.07	0.20	0.003	0.008
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
Н	1.50	1.70	0.059	0.067



SUGGEST PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	0.80	0.031
В	0.60	0.024
С	2.30	0.091



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